

# Cooling system for Reception Tests

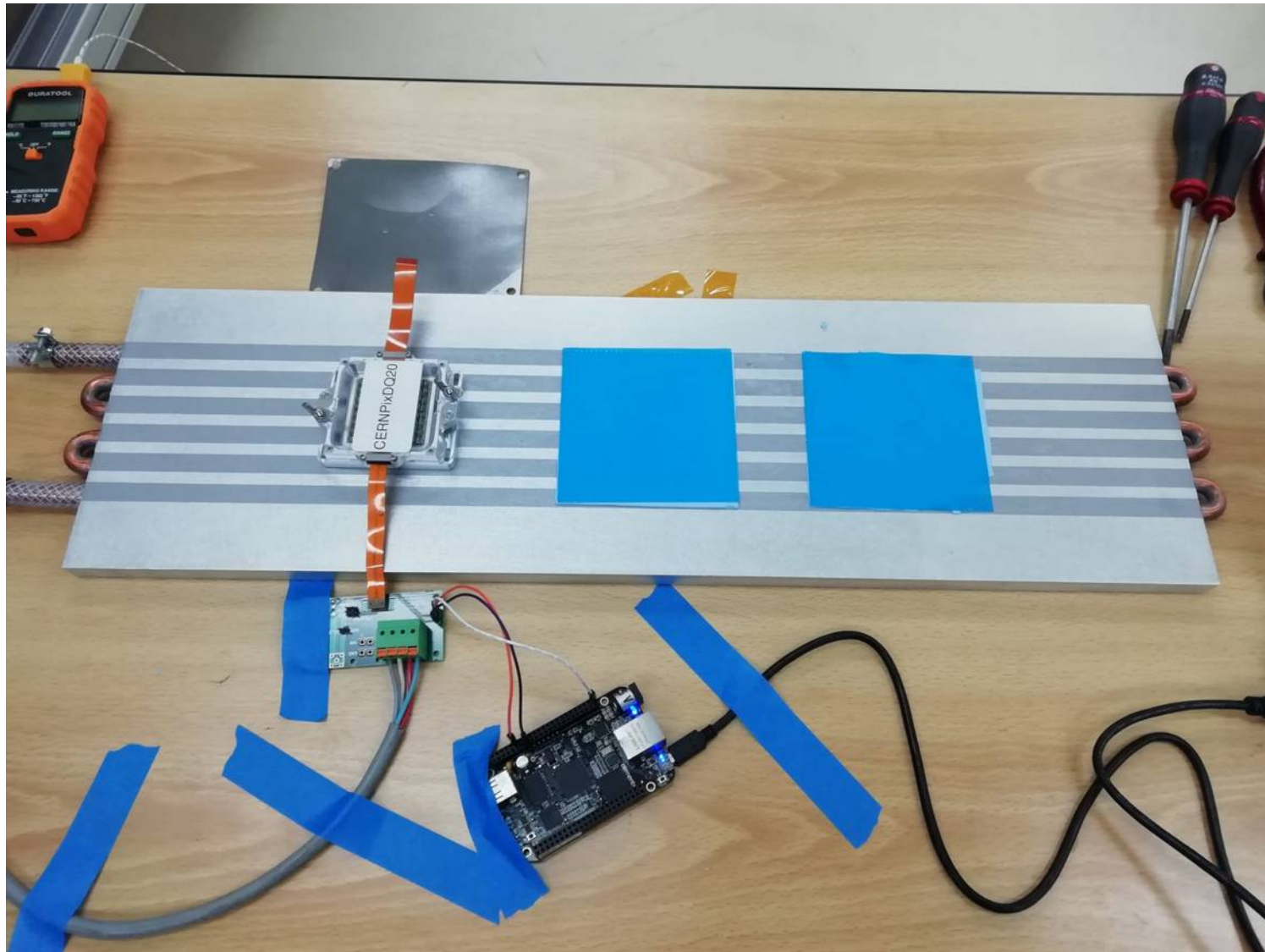
*F. Costanza, R. Gaglione (LAPP)*

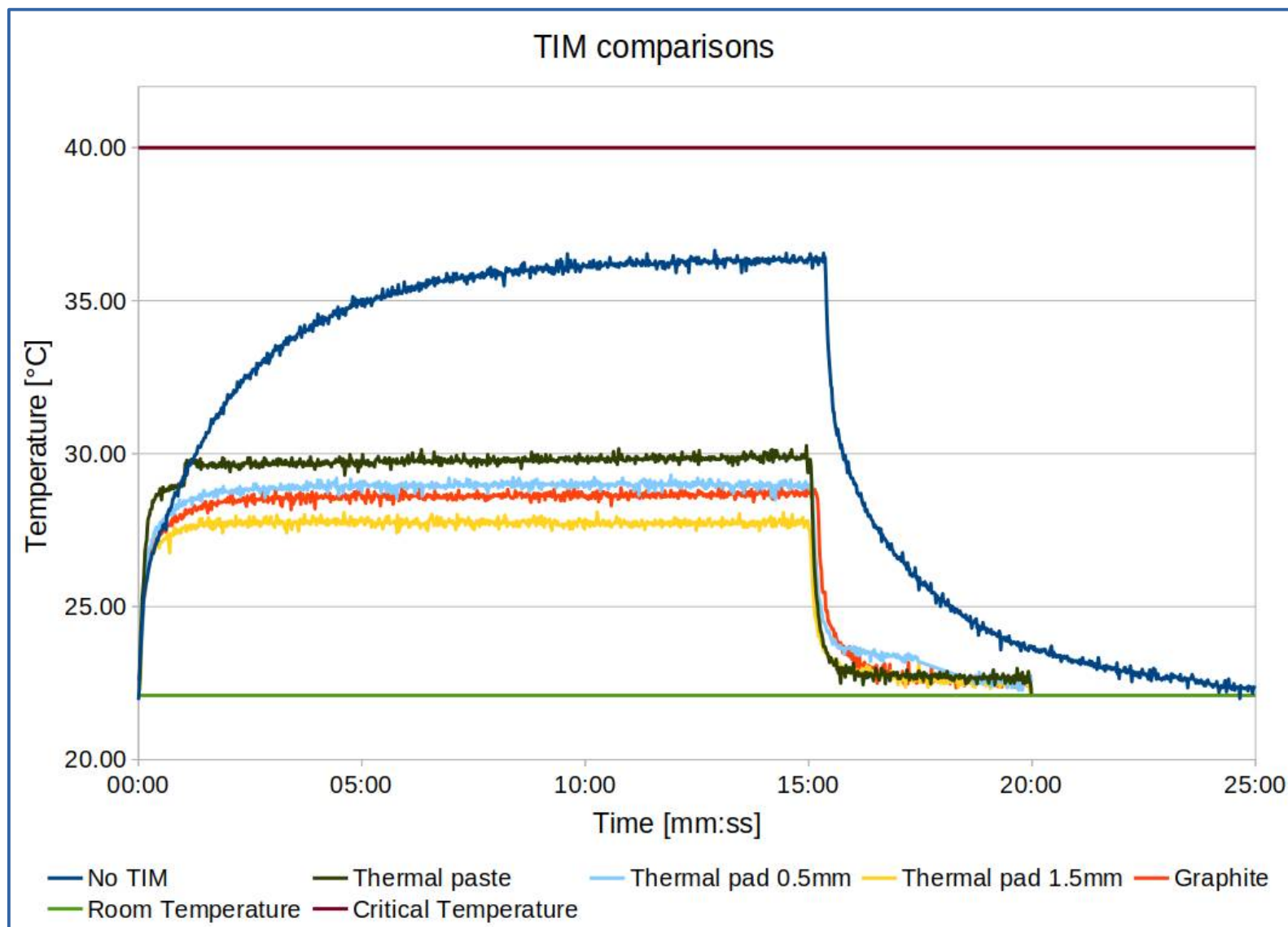
Cell Integration Meeting, November 27<sup>th</sup> 2023

- ◆ **Goal:** Test thermal performance of cooling system for reception tests and first steps of integration site qualification. In particular, test several Thermal Interface Media (TIM).
- ◆ **Procedure:**
  - ◆ Install ITkPix module on the cold plate: thermal contact, power and NTC reading.
  - ◆ Turn on alim at 5.5A. We measure 1.65V drop at the module and ~2V at the PSU with our setup.
  - ◆ Monitor temperature until equilibrium is reached (~15min).
  - ◆ Turn off.
  - ◆ Monitor temperature until equilibrium is reached (~5min).
  - ◆ Repeat with a different TIM.

- ♦ ITkPix module: CERNPixDQ20
  - ♦ NTC TDK B57230V2103F260
- ♦ Chiller: 100W, link
- ♦ Cold plate:
- ♦ PSU:
- ♦ TIMs:
  - ♦ Thermal Paste
  - ♦ Thermal Pads
  - ♦ Graphite Pad







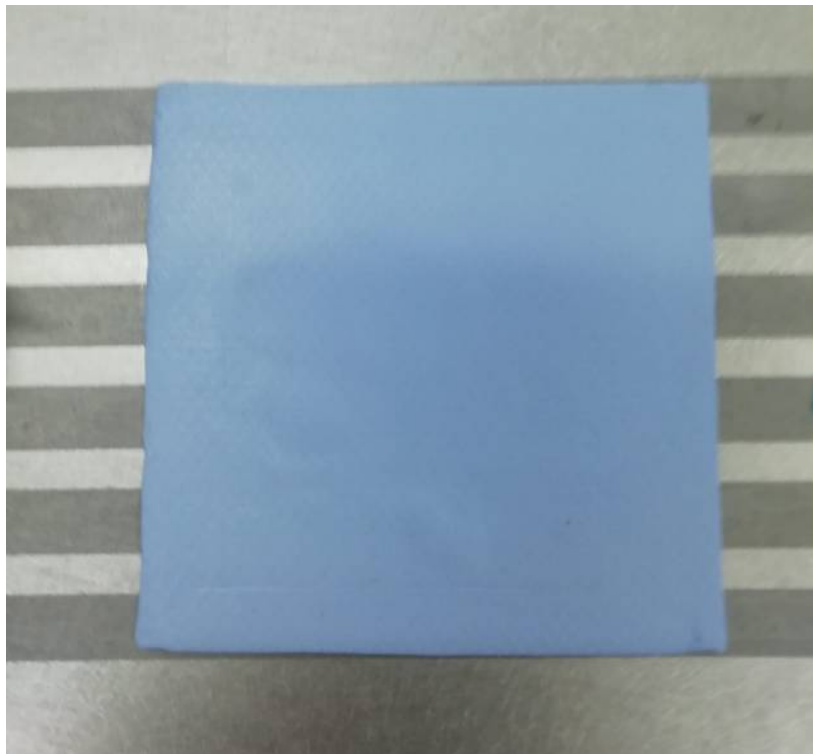
Temperature uncertainty is  $\sim 0.5^{\circ}\text{C}$ , as taken from NTC RT table.

- ♦ Water temperature raised from 21°C to at most 22°C over the whole testing procedure.
- ♦ Thermal paste:
  - ♦ difficult to have homogeneous thickness
  - ♦ difficult to clean
- ♦ Thermal pad:
  - ♦ A bit sticky enough to keep the module well in place
  - ♦ The 1.5mm pad does not tear apart when module is removed
  - ♦ No need to clean the carrier afterwards
- ♦ Graphite pad:
  - ♦ It does not stick to the cold plate
  - ♦ Good thermal contact without applying additional pressure





1.5mm



0.5mm



- ♦ Arctic TP-3 pad 1.5mm thick for the moment is the retained solution for our test stand.